MULTI-SUBSTRATE MICROELECTRONIC PACKAGES AND METHODS FOR MANUFACTURE

ABSTRACT OF THE DISCLOSURE

A microelectronic package and method for manufacture. The package can include first and second microelectronic substrates, each having a first surface with a connection site, and a second surface facing opposite the first surface. The second microelectronic substrate can be coupled to the first microelectronic substrate with the second surface of the second microelectronic substrate facing towards the first surface of the first microelectronic substrate. A conformal conductive link formed, for example, from sequentially deposited portions of conductive material, can be coupled between the first and second connection sites to provide for electrical communication between the substrates. Accordingly, the substrates can be stacked and electrically connected to reduce the footprint occupied by the substrates.

Figure 2D